

10Amp. Trench Schottky Untral Low RECTIFIER

SKT10100LD

$I_{F(AV)}$	10A
V_{RRM}	100V
V_F at 125°C	0.62V
T_j	150°C


Features

- 150°C operating junction temperature
- Softest, fast switching capability
- Reduced ultra-low forward voltage drop (VF) ; better efficiency and cooler operation.
- Lead-Free Finish; RoHS Compliant
- Halogen and Antimony Free. “Green” Device
- Trench technology provides a superior avalanche capability

Mechanical Data

- Case: DO-201AD molded plastic
- Terminals: Plated axial leads, solderable per MIL-STD-750 method
- Polarity: Color band denotes cathode end.
- Epoxy: UL 94V-0 rate flame retardant
- Polarity : As marked.

Maximum Ratings and Electrical Characteristics

(Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.)

Parameter	Symbol	Min.	Typ.	Max.	Units
Maximum DC blocking voltage	V_{DC}			100	V
Maximum Recurrent peak reverse voltage	V_{RRM}			100	V
Maximum RMS voltage	V_{RMS}			70	V
Maximum instantaneous forward voltage at $I_F=10A$	V_F	$T_C=25^\circ C$	0.68	0.72	V
		$T_C=125^\circ C$	0.62	0.66	
Maximum instantaneous reverse current at	I_R	$V_R=100 V, T_C=25^\circ C$	25	80	μA
		$V_R=100 V, T_C=125^\circ C$	12	35	mA
Maximum Average forward rectified current @ $T_C=100^\circ C$	$I_{F(AV)}$			10	A
Non-repetitive peak forward surge current @ 8.3ms single half sine wave superimposed on rated load (JEDEC method)	I_{FSM}	120			A
Peak Repetitive Reverse Surge Current (2 μ S-1Khz)	I_{RRM}			2	A



Storage temperature range	T _{stg}	-55	150	°C
Operating junction temperature range	T _J	-55	150	°C

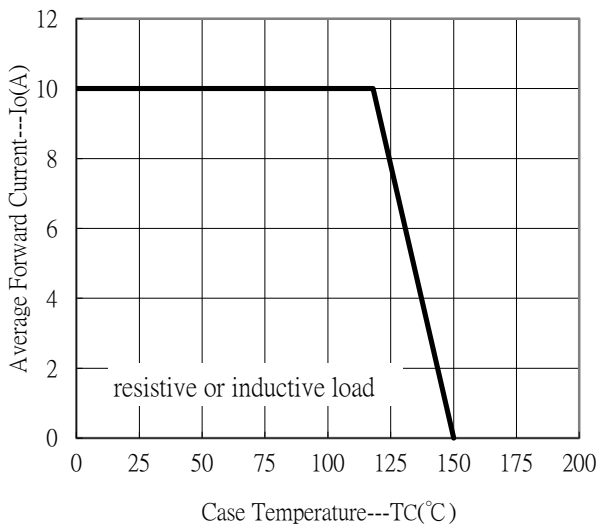
Thermal Data

Parameter	Symbol	Value	Unit
Typical Thermal Resistance, Junction-to-ambient(1)	R _{th,j-a}	60	°C/W
Typical Resistance, Junction-to-lead(2)	R _{th,j-l}	10	°C/W

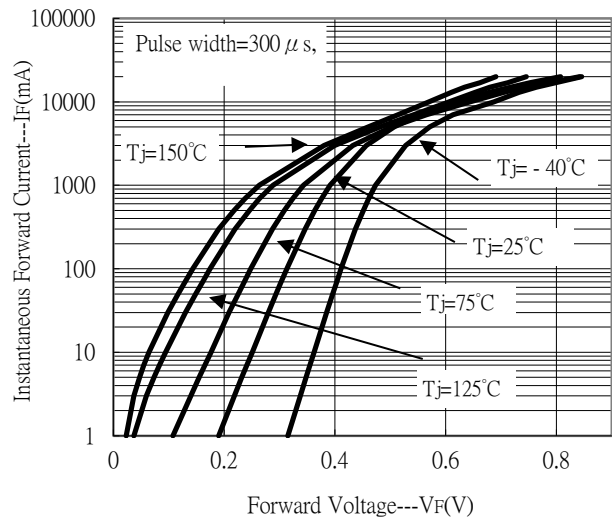
- Note
 1. 10mm lead length between copper pad
 2. Thermal resistance, junction to lead, vertical PCB mounted, 0.375"(9.5mm) lead length

Typical Characteristics

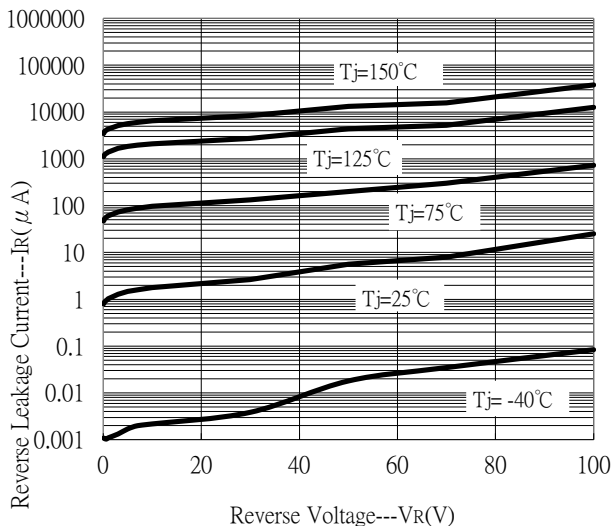
Forward Current Derating Curve



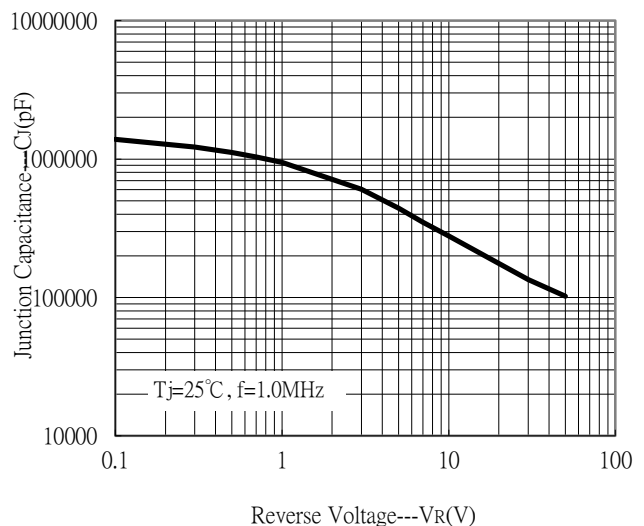
Forward Current vs Forward Voltage



Reverse Leakage Current vs Reverse Voltage



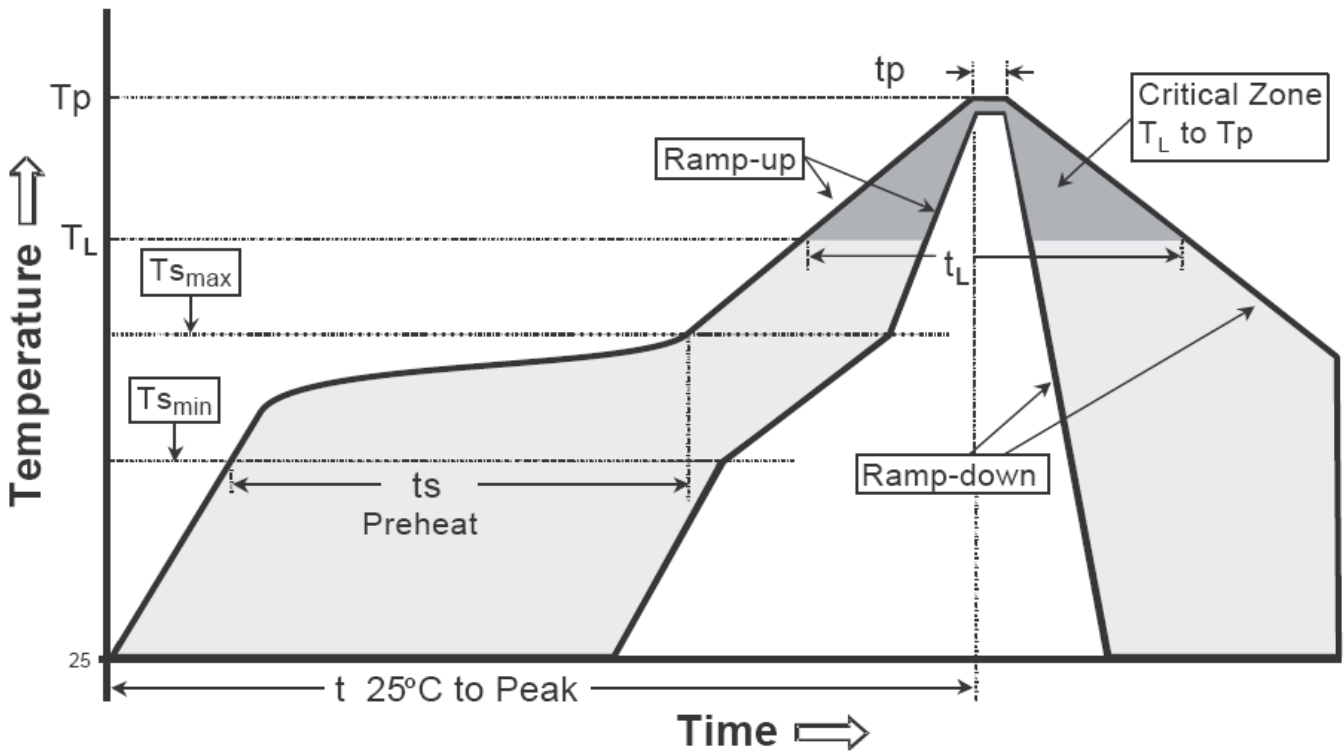
Junction Capacitance vs Reverse Voltage



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

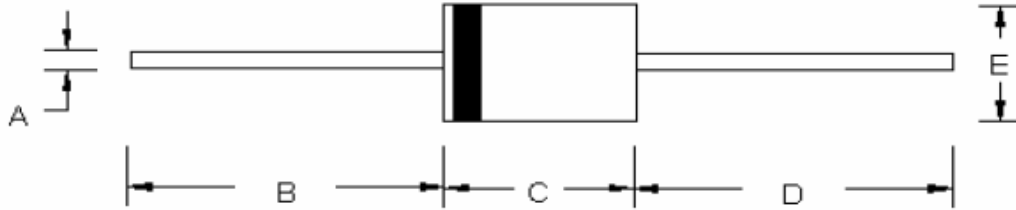
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T _{s min})	100°C	150°C
-Temperature Max(T _{s max})	150°C	200°C
-Time(t _{s min} to t _{s max})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

DO-201AD Dimension



DO-201AD Molded Plastic Package
 CYStek Package Code: LD

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	φ0.048	φ0.052	φ1.20	φ1.30	D	1.000	-	25.40	-
B	1.000	-	25.40	-	E	φ0.190	φ0.210	φ4.80	φ5.30
C	0.285	0.375	7.20	9.50					

Notes : 1. Controlling dimension : millimeters.
 2. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3. If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material :

- Lead : Axial leads, solderable per MIL-STD-750, Method 2026 guaranteed.
- Mold Compound : Epoxy resin family, flammability solid burning class: UL94V-0

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